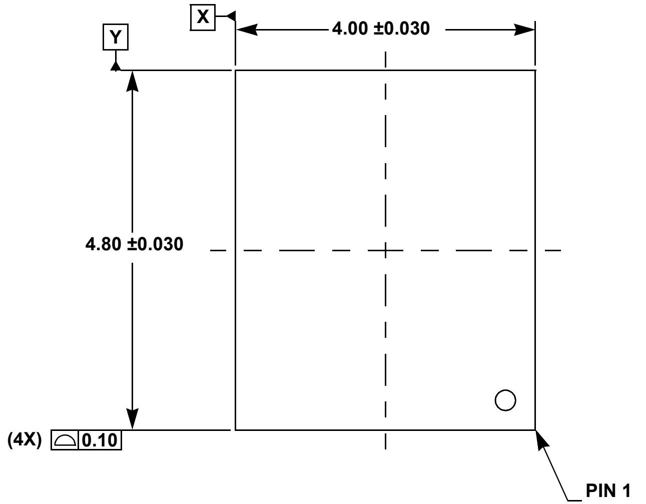
Package Outline Drawing

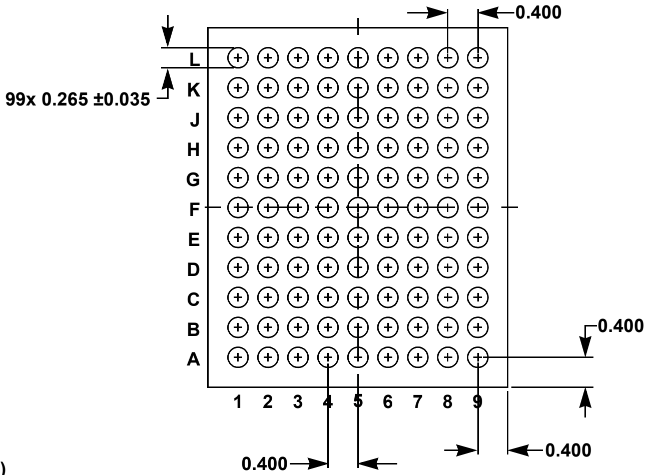
W9x11.99

99 Ball Wafer Level Chip Scale Package (WLCSP 0.4mm Pitch)

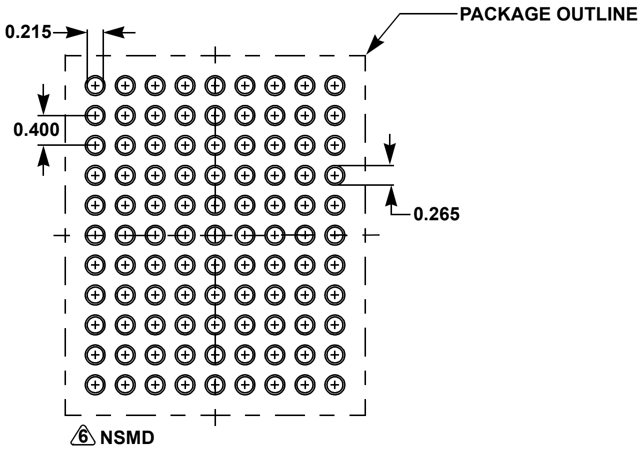
Rev 0, 10/15



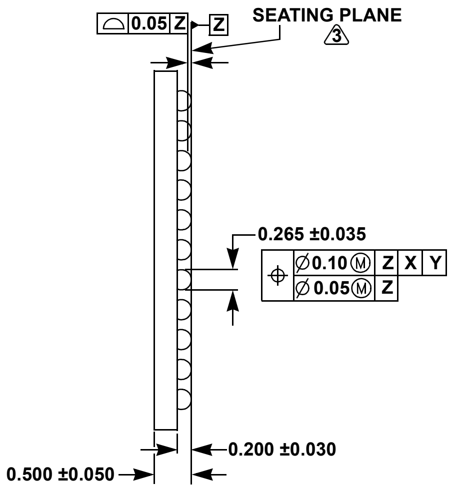
TOP VIEW



BOTTOM VIEW



TYPICAL RECOMMENDED LAND PATTERN



SIDE VIEW

NOTES:

1. All dimensions are in millimeters.
2. Dimensions and tolerance per ASME Y14.5 - 1994.
3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.
4. Dimension is measured at the maximum bump diameter parallel to primary datum Z.
5. Bump position designation per JESD 95-1, SPP-010.
6. NSMD refers to non-solder mask defined pad design per Intersil Techbrief TB451.